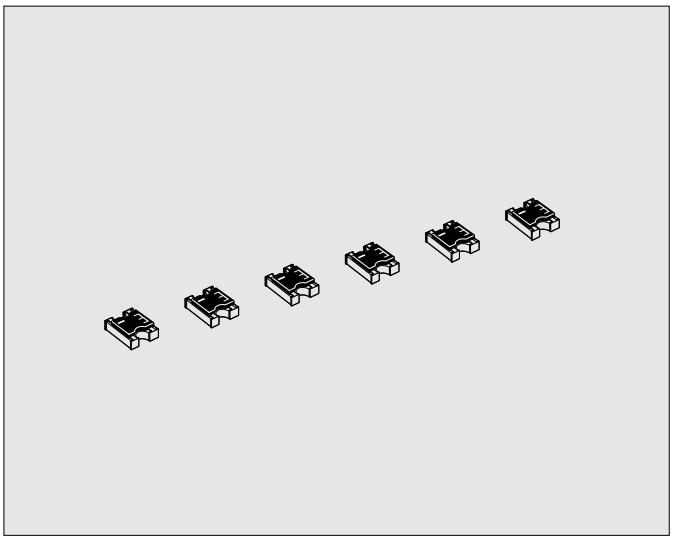
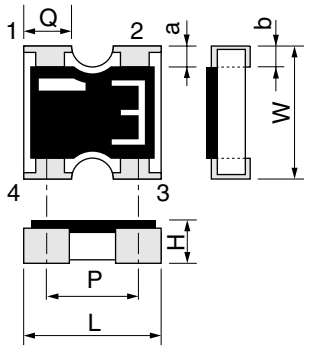
RAC101A

●Features

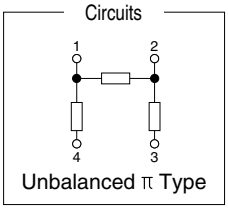
1. Suitable for use at DC and up to UHF band frequencies.
2. Replaceable three discrete resistors with one chip on attenuation circuits.
3. Please contact KAMAYA for Halogen and Antimony free product of RAC101A.



●Dimensions and Circuits



Dot mark on Termination 1
Attenuation factor on Termination 2 to 3



Unit : mm

Style	Terminal Style	L	W	H	Q	a	b	*P	*Unit weight/pc.
RAC101A	**C**	1.0±0.05	1.0±0.05	0.35±0.05	0.33±0.10	0.15±0.10	$0.25^{+0.05}_{-0.10}$	0.65	1.1mg

*Values for reference

●Part Number Description

Example

Style

RAC	10	1	A	1	C	TH

RAC — Product Type

10 — Size

10	W:1.0mm

1 — Characteristic Impedance

1	50 ohm

A — Circuits

A	Unbalanced πType

1 — Attenuation Factor

0	0dB
X	0.5dB
1	1dB
Y	1.5dB
2	2dB
3	3dB
4	4dB
5	5dB
6	6dB
7	7dB
8	8dB
9	9dB
A	10dB
B	11dB
C	12dB
D	13dB
E	14dB
F	15dB
G	16dB
H	17dB
J	18dB
K	19dB
L	20dB

C — Terminal Style

C	Convex Type	With corner

TH — * Packaging & Standard Qty. (Min.)

B	Bulk (Loose Package)	1,000pcs.
TH	Paper Tape (2 mm pitch)	10,000pcs.

*Refer to Tape and Packaging information on pages 54 and 55.

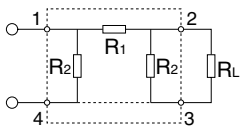
CHIP ATTENUATORS RAC101A

●Ratings

Style	Characteristic Impedance	Attenuation Factor		Tolerance on Attenuation Factor dB	Voltage Standing Wave Ratio	Frequency Range	Rated Input Power mW/package	Category Temperature Range °C
		symbol	dB					
RAC101A	—	0	0	—	—	—	100	–40~+125
	50 ohm	X	0.5	±0.1	1.1max.	DC ≤f ≤3GHz		
		1	1	±0.3	1.2max.			
		Y	1.5					
		2	2					
		3	3					
		4	4					
		5	5					
		6	6	±0.4				
		7	7					
		8	8					
		9	9					
		A	10					
		B	11	±0.8				
		C	12					
		D	13					
		E	14	±1.0				
		F	15	±1.5				
		G	16					
		H	17	±2.0				
		J	18					
		K	19					
		L	20	±2.5				

Note. The following information is available.
1. Test methods for Attenuation Factor and VSWR characteristics.

●Performance Characteristics JIS C 5201-1 : 1998

Description	Requirements			Test Methods
	0.5~2dB	3dB~5dB	6dB~20dB	
Characteristic impedance	50 ohm			Measuring Circuits  RL=50 ohm
Insulation resistance	At least 100M ohm			50Vd.c., 60s
Solderability	In accordance with Clause 4.17.4.5			Clause 4.17 Dip into 235°C Solder bath for 2s.
Resistance to soldering heat	Within ±0.1dB	Within ±0.2dB	Within ±0.3dB	Clause 4.18 Dip into 260°C Solder bath for 5s.
	No major visible damage.			
Rapid change of temperature	Within ±0.1dB	Within ±0.2dB	Within ±0.3dB	Clause 4.19 5 cycles between –55°C and +125°C.
	No major visible damage.			
Endurance at 85˚C	Within ±0.1dB	Within ±0.2dB	Within ±0.3dB	Clause 4.25.1 Rated input power, 1.5h"ON", 0.5h"OFF", 85°C, 1,000h.
Bend strength of the face plating	Within ±0.1dB	Within ±0.2dB	Within ±0.3dB	Clause 4.33 Amount of bend : 3 mm